

XINGSHENG LIU

WORK EXPERIENCE

- Professor, Xi'an Institute of Optics and Precision Mechanics, Chinese Academy of Science (October 2007-now).
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- CEO and President, Xi'an Focuslight Technologies Co., LTD (March 2008-now).
- Director of Process Engineering, nLight Photonics Corp., (December 2006-October 2007):
- Sr. Staff Engineer, Semiconductor Business Unit, Coherent Inc. (March 2006-December 2006):
- Sr. Research Scientist, Science and Technology Center, Corning Inc. (March 2001-March 2006):
- Graduate Research Assistant, Center for Power Electronics Systems, Virginia Tech (August 1998 - February, 2001):

EDUCATION

- **Ph.D. in Electronic Packaging-Materials Science & Engineering**, February 2001, Virginia Tech, Blacksburg, VA.
- **M.S. in Condensed Matter Physics**, July 1998, Beijing University, Beijing, China.
- **B.S. in Physics**, July 1995, Shaanxi Normal University, Xi'an, China.

HONORS & AWARDS

- Member of the China "Recruitment Program of Global Experts".
- Paul E. Torgersen Research Excellence Award-the First Prize, Virginia Tech, Blacksburg, VA, 2001.
- Best paper of session award at the 33rd International Symposium on Microelectronics –IMAPS (International Microelectronics And Packaging Society) 2000, Boston, Massachusetts, September 20-22, 2000.

PROFESSIONAL ACTIVITIES & CONTRIBUTIONS

- Co-Chair of Optoelectronics Technical Committee, IEEE Electronic Components and Technology Conference (ECTC), 2004-2009.
- Optoelectronics Technical Committee Member, IEEE Electronic Components and Technology Conference (ECTC), 2004-2009.
- Program Committee Member of Photonics Packaging, Integration and Interconnects conference, SPIE Photonics West, 2006-2007.
- Session Chair, IEEE Electronic Components and Technology Conference (ECTC 2007), 2008.
- Session Chair, IEEE Electronic Components and Technology Conference (ECTC 2007), 2007.

- Session Chair, IEEE Electronic Components and Technology Conference (ECTC 2006), San Diego, California, May 30 - June 2, 2006.
- Session Chair and Technical Committee Member, International Conference on Thermal and Thermalmechanical Phenomena in Electronics Systems (ITherm), Las Vegas, Nevada, June 1-4, 2004.
- Session Co-Chair and Technical Committee Member, International Conference on Thermal and Thermalmechanical Phenomena in Electronics Systems (ITherm), San Diego, CA, May 29-June 1, 2002.
- Served as a panelist in the panel discussion of “Challenges in the Optical and Electronic Packaging of Data/Voice Equipments” in the International Conference on Thermal and Thermalmechanical Phenomena in Electronics Systems (ITherm), San Diego, CA, May 29-June 1, 2002.
- Paper Reviewer, IEEE Transactions on Advanced Packaging.
- Paper Reviewer, IEEE Transactions on Components and Packaging Technologies.
- Paper Reviewer, IEEE Transactions on Electron Devices.
- Paper Reviewer, Journal of Electronic Packaging.
- Paper Reviewer, the journal of Microelectronics Reliability.
- Senior Member, IEEE and IEEE Components, Packaging and Manufacturing Technology Society.

PUBLICATIONS

Over 80 papers published in journals and conference proceedings. Over 20 patents granted.